

## Power Supply Supervisory Circuit

### FEATURES

- Includes Over-Voltage, Under-Voltage, and Current Sensing Circuits
- Internal 1% Accurate Reference
- Programmable Time Delays
- SCR “Crowbar” Drive of 300 mA
- Remote Activation Capability
- Optional Over-Voltage Latch
- Uncommitted Comparator Inputs for Low Voltage Sensing (UC1544 Series Only)

### DESCRIPTION

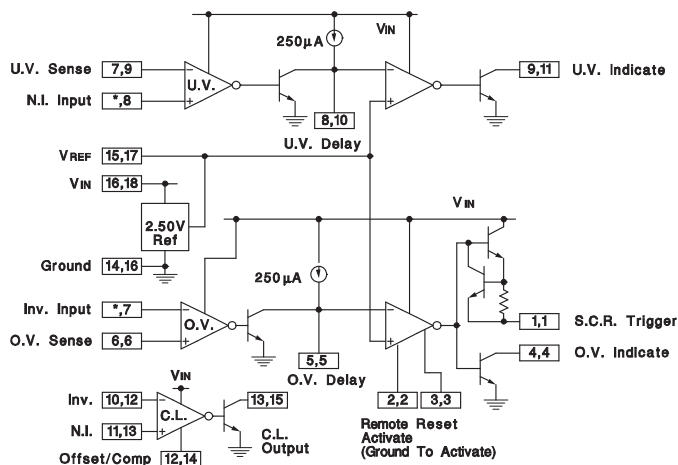
The monolithic integrated circuits contain all the functions necessary to monitor and control the output of a sophisticated power supply system. Over-voltage (O.V.) sensing with provision to trigger an external SCR “crowbar” shutdown; an undervoltage (U.V.) circuit which can be used to monitor either the output or to sample the input line voltage; and a third op amp/comparator usable for current sensing (C.L.) are all included in this device, together with an independent, accurate reference generator.

Both over- and under-voltage sensing circuits can be externally programmed for minimum time duration of fault before triggering. All functions contain open collector outputs which can be used independently or wire-or’ed together, and although the SCR trigger is directly connected only to the over-voltage sensing circuit, it may be optionally activated by any of the other outputs, or from an external signal. The O.V. circuit also includes an optional latch and external reset capability.

The UC1544/2544/3544 devices have the added versatility of completely uncommitted inputs to the voltage sensing comparators so that levels less than 2.5 V may be monitored by dividing down the internal reference voltage. The current sense circuit may be used with external compensation as a linear amplifier or as a highgain comparator. Although nominally set for zero input offset, a fixed threshold may be added with an external resistor. Instead of current limiting, this circuit may also be used as an additional voltage monitor.

The reference generator circuit is internally trimmed to eliminate the need for external potentiometers and the entire circuit may be powered directly from either the output being monitored or from a separate bias voltage.

### BLOCK DIAGRAM



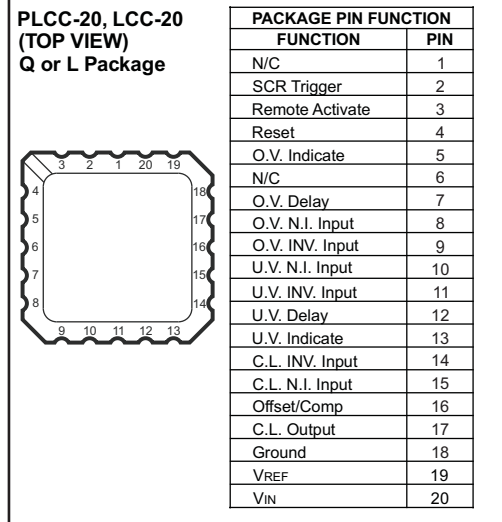
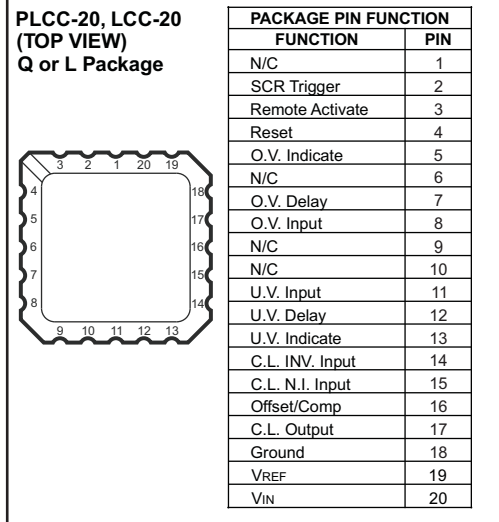
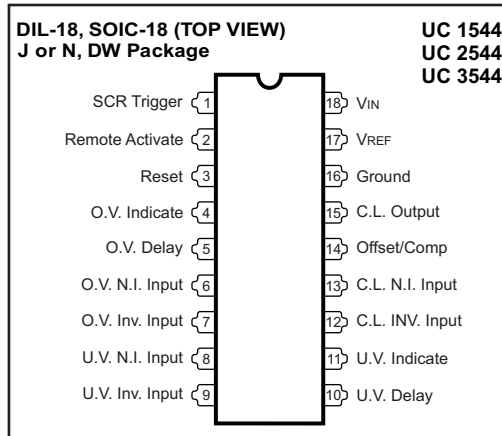
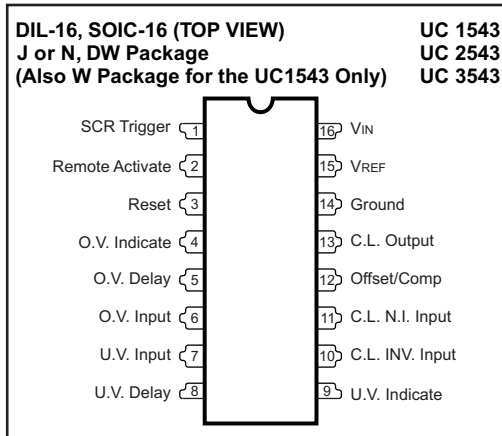
### NOTE:

For each terminal, first number refers to 1543 series, second to 1544 series.  
\*On 1543 series, this function is internally connected to VREF.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

## Connection Diagrams



## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		VALUE	UNIT
$V_{IN}$	Input supply voltage	40	V
	Sense inputs, voltage range	0 to $V_{IN}$	
	SCR trigger current <sup>(2)</sup>	-600	mA
	Indicator output voltage	40	V
	Indicator output sink current	50	mA
	Power dissipation (package limitation)	1000	mW
$T_J$	Operating temperature range	UC1543, UC1544	°C
		UC2543, UC2544	
		UC3543, UC3544	
$T_{stg}$	Storage temperature range	-65 to 150	

(1) Currents are positive-into, negative-out of the specified terminal.

(2) At higher input voltages, a dissipation limiting resistor,  $R_G$ , is required.

## ELECTRICAL CHARACTERISTICS

Unless otherwise stated, these specifications apply for  $T_A = -55^\circ\text{C}$  to  $125^\circ\text{C}$  for the UC1543 and UC1544;  $-25^\circ\text{C}$  to  $85^\circ\text{C}$  for the UC2543 and UC2544; and  $0^\circ\text{C}$  to  $70^\circ\text{C}$  for the UC3543 and UC3544. Electrical tests are performed with  $V_{IN} = 10\text{ V}$  and 2-k $\Omega$  pull-up resistors on all indicator outputs. All electrical specifications for the UC1544, UC2544, and UC3544 devices are tested with the inverting over-voltage input and the non-inverting under-voltage input externally connected to the 2.5 V reference.  $T_A = T_J$ .

PARAMETER		TEST CONDITIONS	UC1543/UC1544/UC2543/ UC2544			UC3543/UC3544			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
$V_{IN}$	Input voltage range	$T_J = 25^\circ\text{C}$ to $T_{MAX}$	4.5		40	4.5		40	V
		$T_{MIN}$ to $T_{MAX}$	4.7		40	4.7		40	
$I_{CC}$	Supply current	$V_{IN} = 40\text{ V}$ , output open, $T_J = 25^\circ\text{C}$		7	10		7	10	mA
		$T_{MIN} \leq T_J \leq T_{MAX}$			15			15	
<b>Reference Section</b>									
$V_{OUT}$	Output voltage	$T_J = 25^\circ\text{C}$	2.48	2.5	2.52	2.45	2.50	2.55	V
		Over temperature range	2.45		2.55	2.40		2.60	
	Line regulation	$V_{IN} = 5$ to $30\text{ V}$		1	5		1	5	mV
	Load regulation	$I_{REF} = 0$ to $10\text{ mA}$		1	10		1	10	
	Short circuit current	$V_{REF} = 0$	-10	-20	-40	-12	-20	-40	mA
	Temperature stability			50			50		ppm/ $^\circ\text{C}$
<b>SCR Trigger Section</b>									
	Peak output current	$V_{IN} = 5\text{ V}$ , $R_G = 0$ , $V_O = 0$	-100	-300	-600	-100	-300	-600	mA
	Peak output voltage	$V_{IN} = 15\text{ V}$ , $I_O = -100\text{ mA}$	12	13		12	13		V
	Output OFF voltage	$V_{IN} = 40\text{ V}$		0	0.1		0	0.1	
	Remote activate current	R/A Pin = GND		-0.4	-0.8		-0.4	-0.8	mA
	Remote activate voltage	R/A Pin Open		2	6		2	6	V
	Reset current	Reset = GND, R/A = GND		-0.4	-0.8		-0.4	-0.8	mA
	Reset voltage	Reset open, R/A = GND		2	6		2	6	V
	Output current rise time	$R_L = 50$ , $T_J = 25^\circ\text{C}$ , $C_D = 0$		400			400		mA/ $\mu\text{s}$
	Prop. delay from R/A	$R_L = 50$ , $T_J = 25^\circ\text{C}$ , $C_D = 0$		300			300		ns
	Prop. delay from O/V input	$R_L = 50$ , $T_J = 25^\circ\text{C}$ , $C_D = 0$		500			500		
<b>Comparator Section</b>									
	Input threshold (Input voltage rising on O.V. and falling on U.V.)	$T_J = 25^\circ\text{C}$	2.45	2.50	2.55	2.40	2.50	2.60	V
		Over temperature range	2.40		2.60	2.35		2.65	
	Input hysteresis			25			25		mV
	Input bias current	Sense input = 0 V		-0.3	-1.0		-0.3	-1.0	$\mu\text{A}$
	Delay saturation			0.2	0.5		0.2	0.5	V
	Delay high level			6	7		6	7	
	Delay charging current	$V_O = 0$	-200	-250	-300	-200	-250	-300	$\mu\text{A}$
	Indicate saturation	$I_L = 10\text{ mA}$		0.2	0.5		0.2	0.5	V
	Indicate leakage	$V_{IND} = 40\text{ V}$		0.01	1.0		0.01	1.0	$\mu\text{A}$
	Propagation delay	Input over drive = 200 mV, $T_J = 25^\circ\text{C}$ , $C_D = 0$		400			400		ns
		Input over drive = 200 mV, $T_J = 25^\circ\text{C}$ , $C_D = 1\ \mu\text{F}$		10			10		ms

**ELECTRICAL CHARACTERISTICS (continued)**

Unless otherwise stated, these specifications apply for  $T_A = -55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$  for the UC1543 and UC1544;  $-25^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  for the UC2543 and UC2544; and  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$  for the UC3543 and UC3544. Electrical tests are performed with  $V_{IN} = 10\text{ V}$  and 2-k $\Omega$  pull-up resistors on all indicator outputs. All electrical specifications for the UC1544, UC2544, and UC3544 devices are tested with the inverting over-voltage input and the non-inverting under-voltage input externally connected to the 2.5 V reference.  $T_A = T_J$ .

Current Limit Section								
Input voltage range		0		VIN -3V	0		VIN -3V	V
Input Bias Current	Offset pin open, $V_{CM} = 0$		-0.3	-1.0		-0.3	-1.0	$\mu\text{A}$
Input offset voltage	Offset pin open, $V_{CM} = 0$		0	10		0	10	mV
	10k from offset pin to GND	80	100	120	80	100	120	
CMRR	$0 \leq V_{CM} \leq 12\text{ V}$ , $V_{IN} = 15\text{ V}$	60	70		60	70		dB
AVOL	Offset pin open, $V_{CM} = 0$ $V_i$ , $R_L = 10\text{ k}\Omega$ to $15\text{ k}\Omega$ , $V_{OUT} = 1$ to $6\text{ V}$	72	80		72	80		
Output saturation	$I_L = 10\text{ mA}$		0.2	0.5		0.2	0.5	V
Output leakage	$V_{IND} = 40\text{ V}$		0.01	1.0		0.01	1.0	$\mu\text{A}$
Small signal bandwidth	$A_V = 0\text{ dB}$ , $T_J = 25^{\circ}\text{C}$		5			5		MHz
Propagation delay	$V_{OVERDRIVE} = 100\text{ mV}$ , $T_J = 25^{\circ}\text{C}$		200			200		ns

**TYPICAL CHARACTERISTICS**

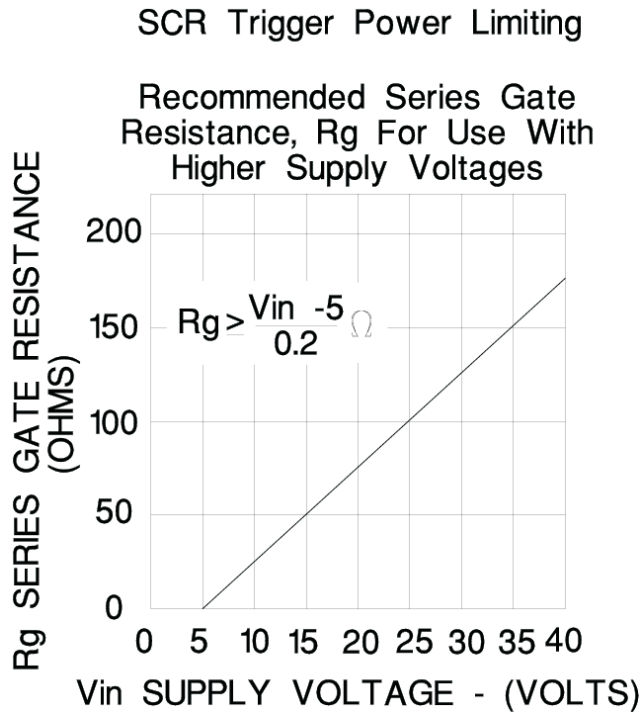


Figure 1.

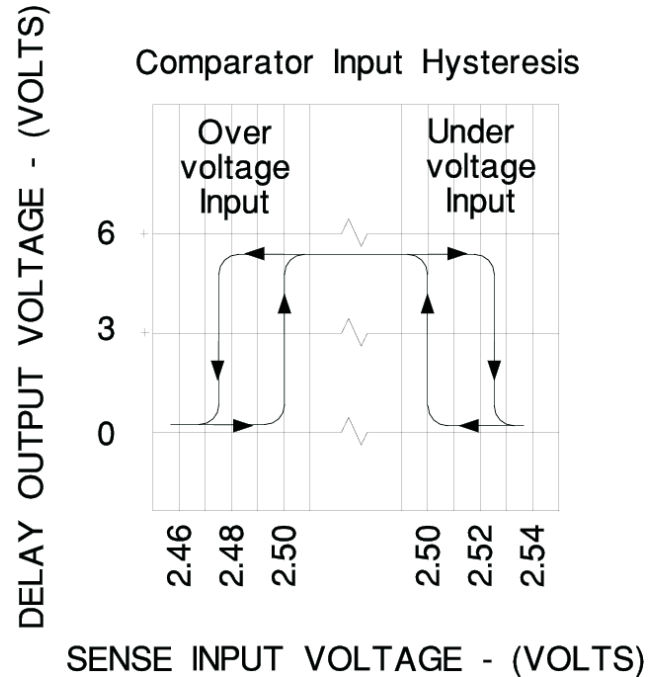


Figure 2.

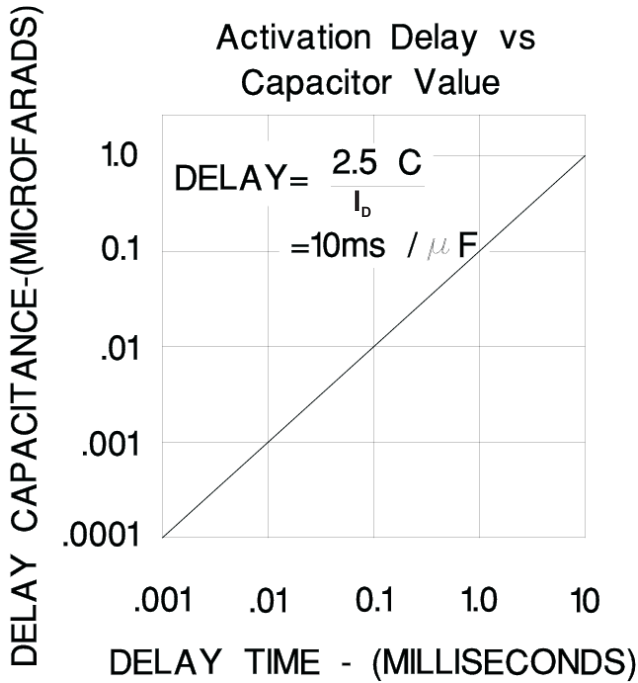


Figure 3.

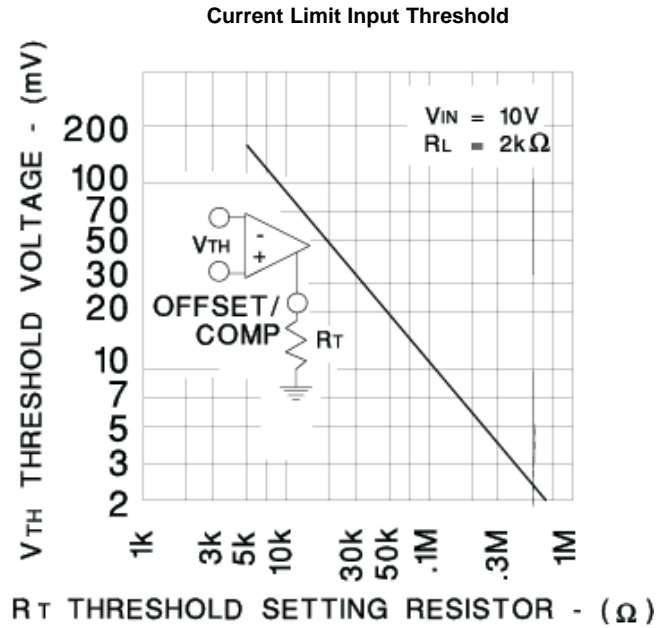


Figure 4.

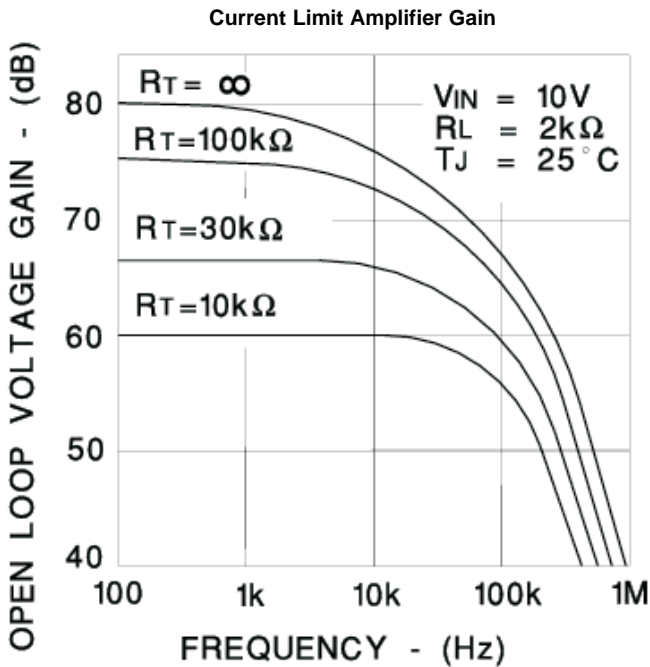


Figure 5.

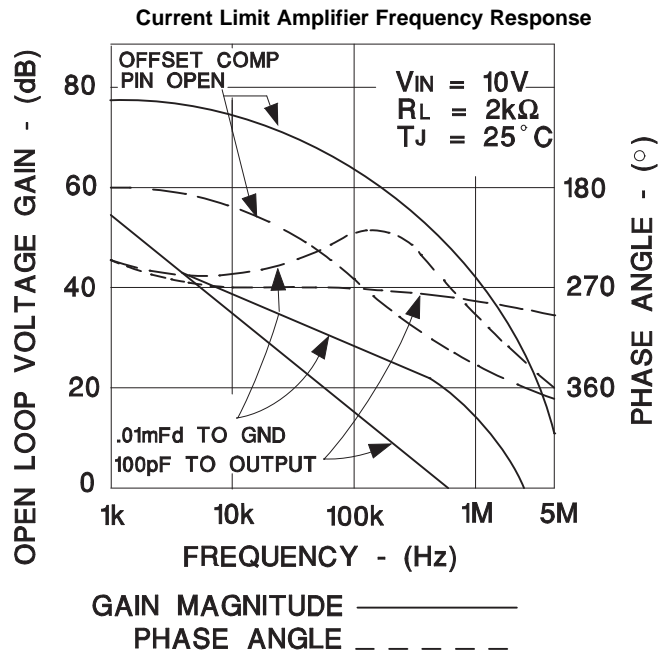


Figure 6.

### APPLICATION INFORMATION

The values for the external components are determined as follows:

$$V_{TH} = \frac{1000}{R1}$$

Current limit input threshold,

$C_S$  is determined by the current loop dynamics

$$I_P \cong \frac{V_{TH}}{R_{SC}} + \frac{V_O}{R_{SC}} \left( \frac{R2}{R2 + R3} \right)$$

Peak current to load,

$$I_{SC} = \frac{V_{TH}}{R_{SC}}$$

Short circuit current,

$$V_{O(low)} = \frac{2.5(R4 + R5 + R6)}{R5 + R6}$$

Low output voltage limit,

$$V_{O(high)} = \frac{2.5(R4 + R5 + R6)}{R6}$$

High output voltage limit,

Voltage sensing delay,  $t_D = 10,000C_d$

$$R_G > \frac{V_{IN} - 5}{0.2}$$

SCR trigger power limiting resistor,

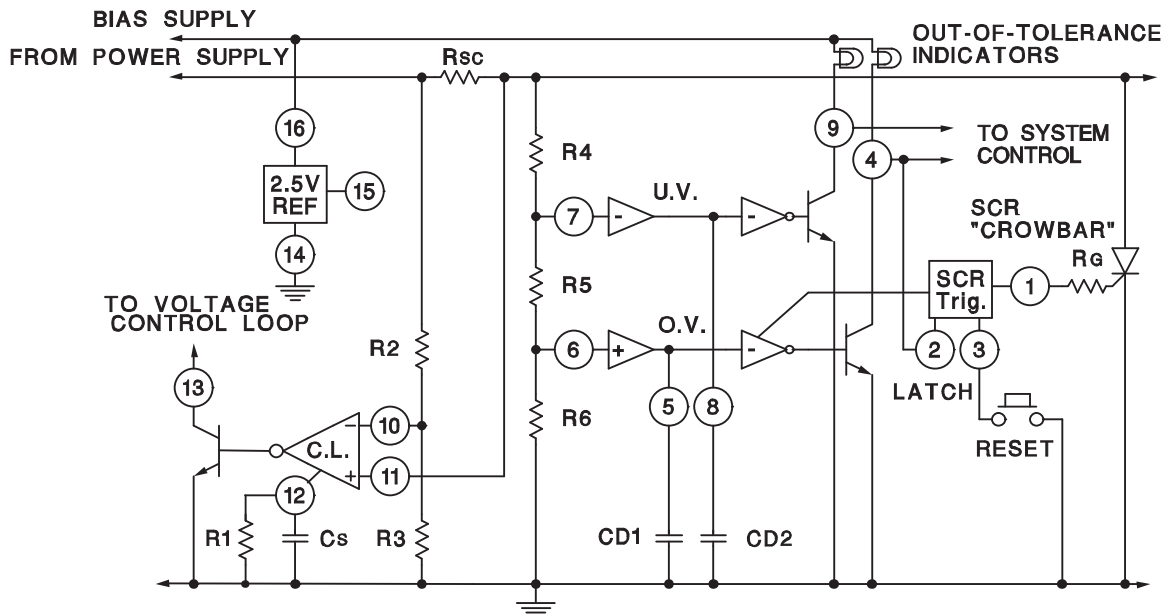


Figure 7. Typical Application

APPLICATION INFORMATION (continued)

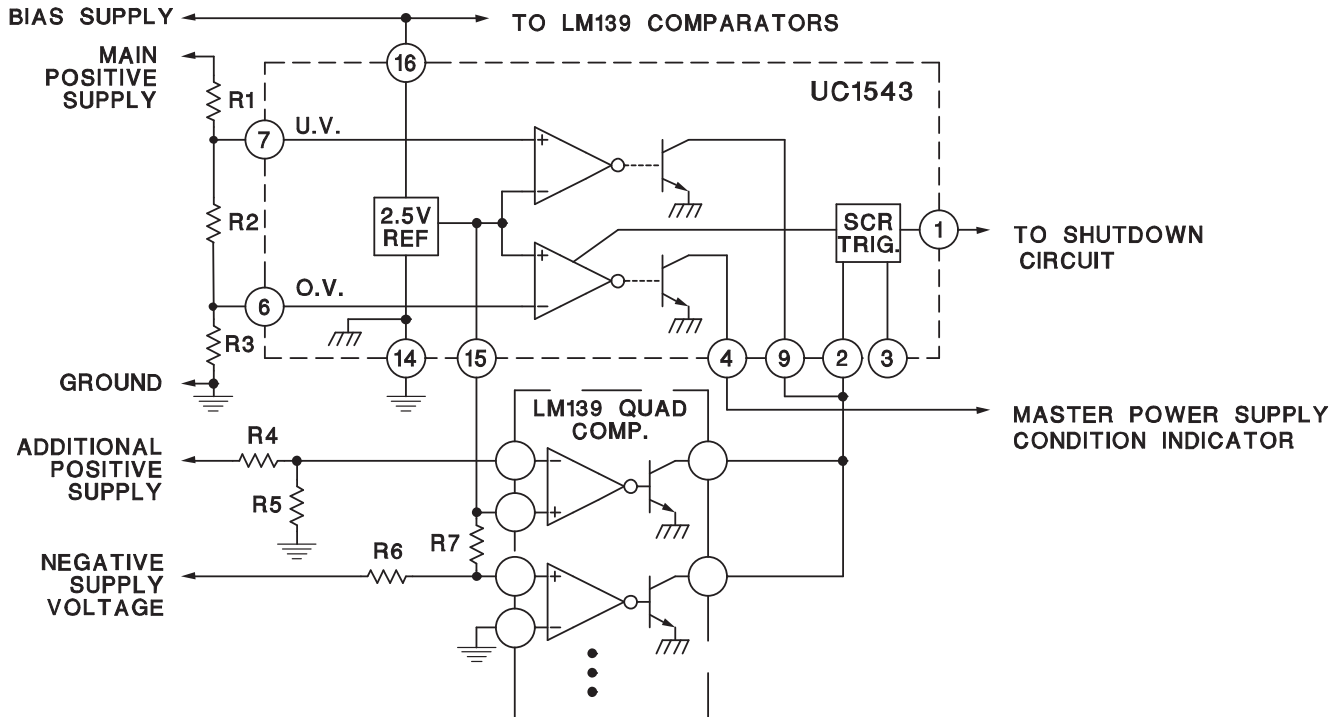


Figure 8. Sensing Multiple Supply Voltages

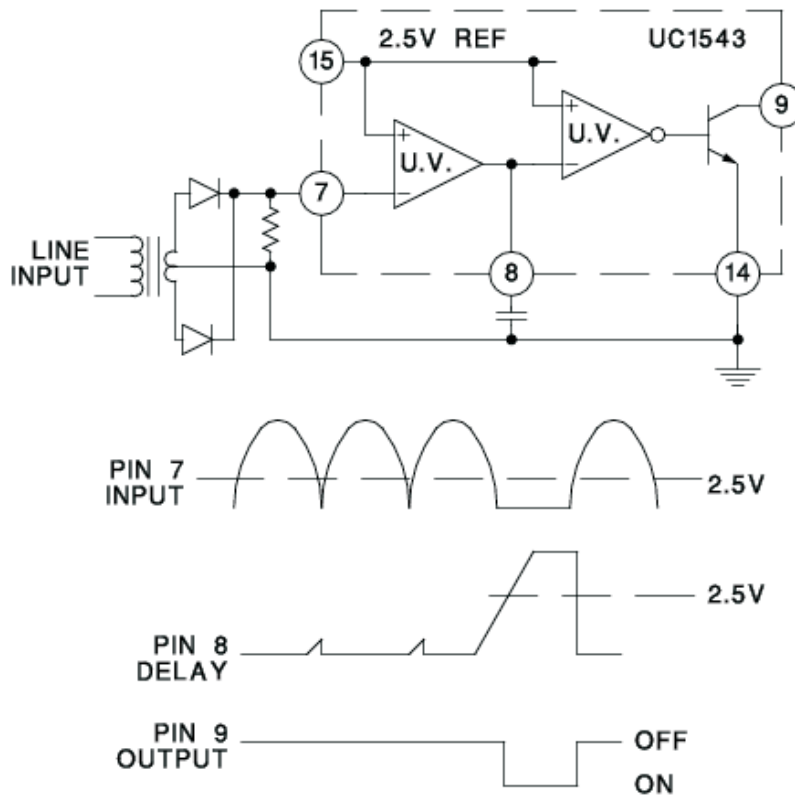


Figure 9. Input Line Monitor

APPLICATION INFORMATION (continued)

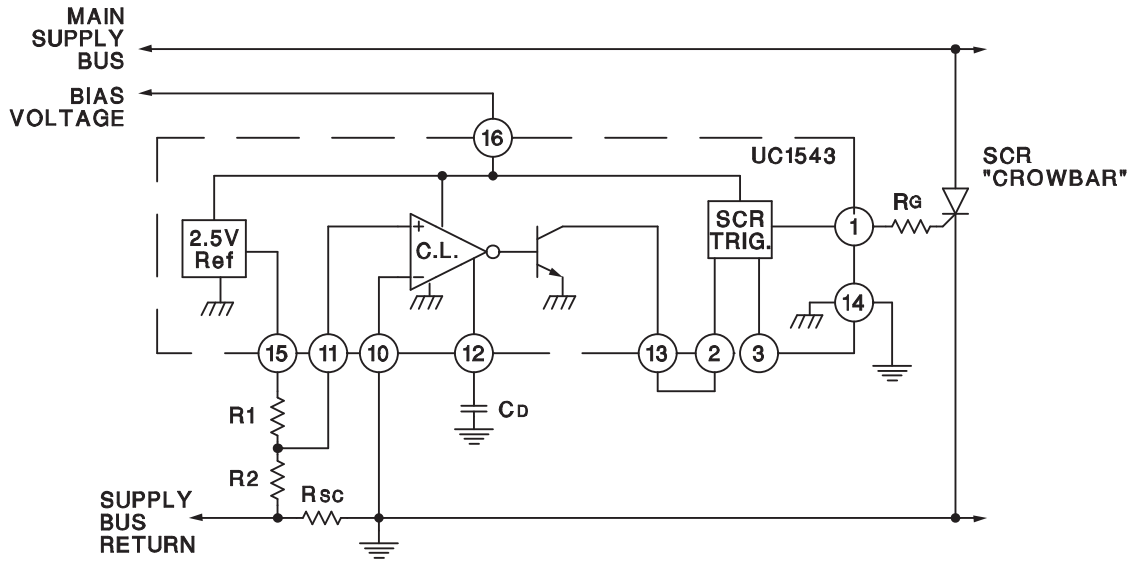


Figure 10. Overcurrent Shutdown



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8774001EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8774001EA UC1543J/883B	<a href="#">Samples</a>
5962-8774001FA	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type		5962-8774001FA UC1543W/883B	<a href="#">Samples</a>
5962-8774002VA	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI	-55 to 125		
UC1543J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	UC1543J	<a href="#">Samples</a>
UC1543J883B	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8774001EA UC1543J/883B	<a href="#">Samples</a>
UC1543L	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	UC1543L	<a href="#">Samples</a>
UC1543L883B	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	UC1543L/ 883B	<a href="#">Samples</a>
UC1543W883B	ACTIVE	CFP	W	16	25	TBD	A42	N / A for Pkg Type		5962-8774001FA UC1543W/883B	<a href="#">Samples</a>
UC1544J	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI	-55 to 125		
UC1544J883B	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI	-55 to 125		
UC1544L	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
UC1544L883B	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI	-55 to 125		
UC2543DW	NRND	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2543DW	
UC2543DWG4	NRND	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2543DW	
UC2543J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-25 to 85	UC2543J	<a href="#">Samples</a>
UC2543N	NRND	PDIP	N	16	25	TBD	Call TI	Call TI	-40 to 85	UC2543N	
UC2543NG4	NRND	PDIP	N	16	25	TBD	Call TI	Call TI	-40 to 85	UC2543N	
UC2544-W	ACTIVE	WAFERSALE	YS	0		TBD	Call TI	Call TI			<a href="#">Samples</a>
UC2544DW	NRND	SOIC	DW	18	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UC2544DW	
UC2544J	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI	-40 to 85		
UC3543J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	0 to 70	UC3543J	<a href="#">Samples</a>

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UC3543N	NRND	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UC3543N	
UC3543NG4	NRND	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	0 to 70	UC3543N	
UC3544J	OBSOLETE	CDIP	J	18		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF UC1543, UC1544, UC2543, UC2543M, UC3543, UC3543M, UC3544 :**

- Catalog: [UC3543](#), [UC3544](#), [UC2543](#), [UC3543M](#), [UC3543](#)
- Military: [UC2543M](#), [UC1543](#), [UC1543](#), [UC1544](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP2-F16

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

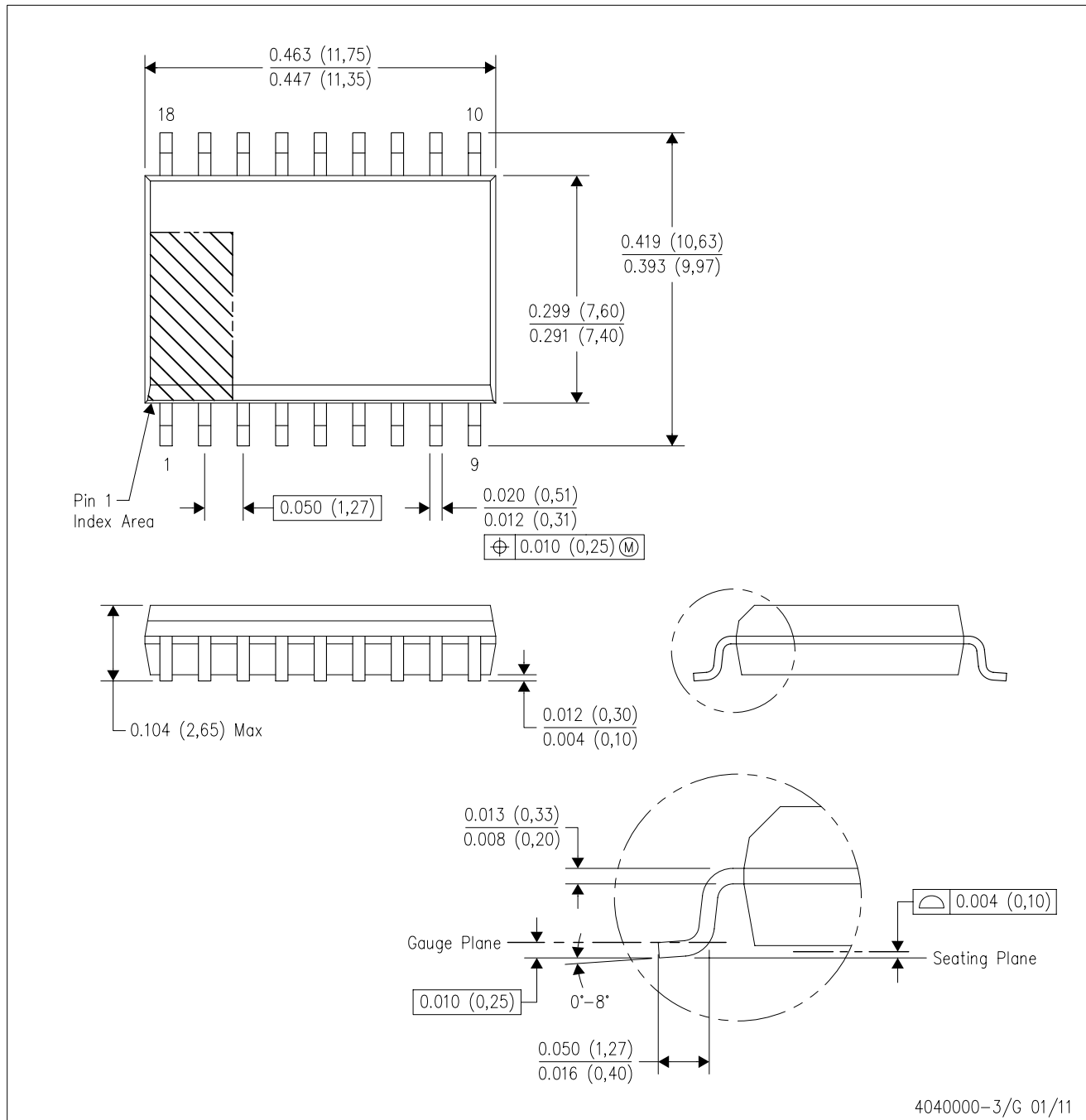
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G18)

PLASTIC SMALL OUTLINE

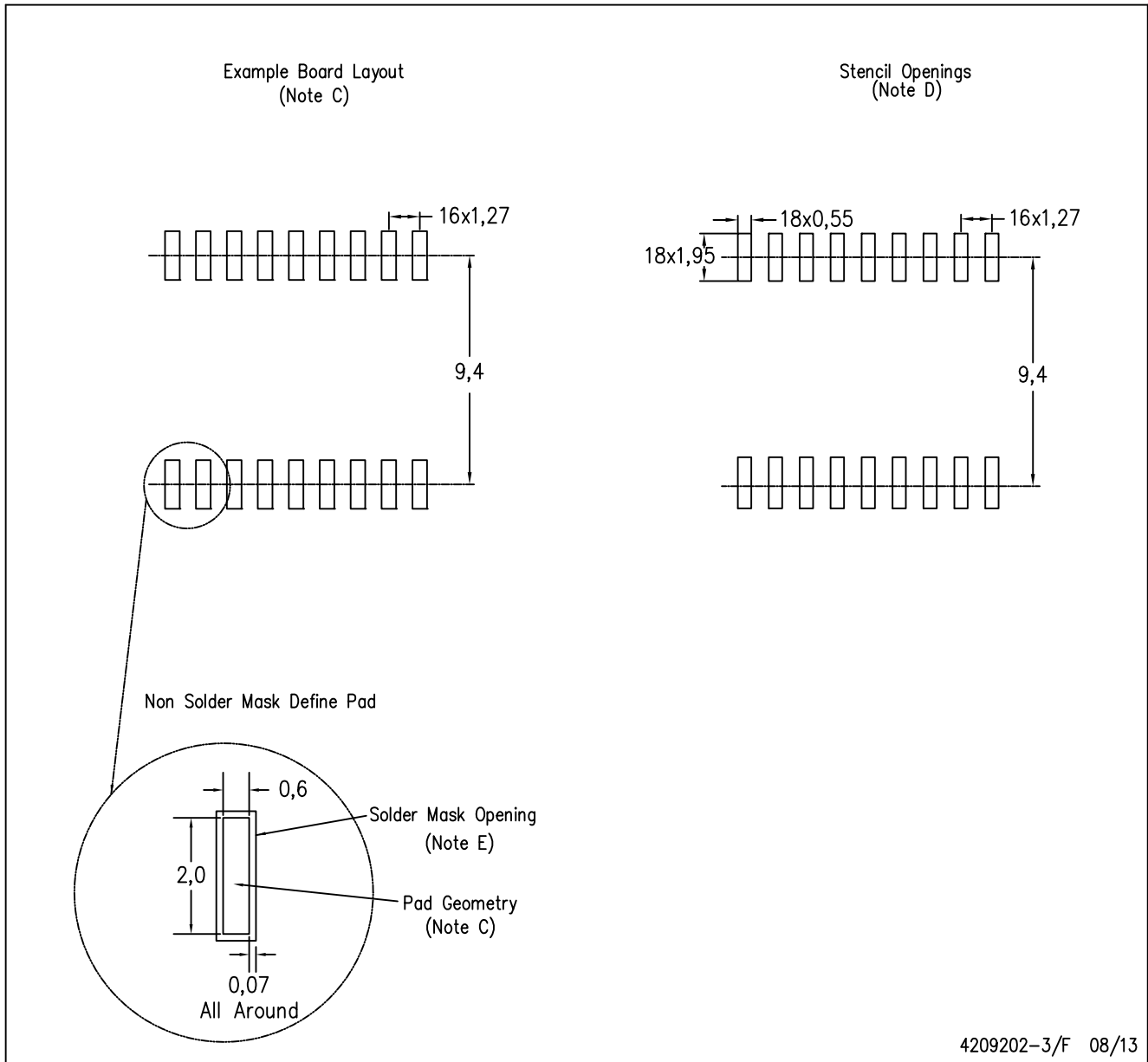


- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AB.



DW (R-PDSO-G18)

PLASTIC SMALL OUTLINE



4209202-3/F 08/13

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

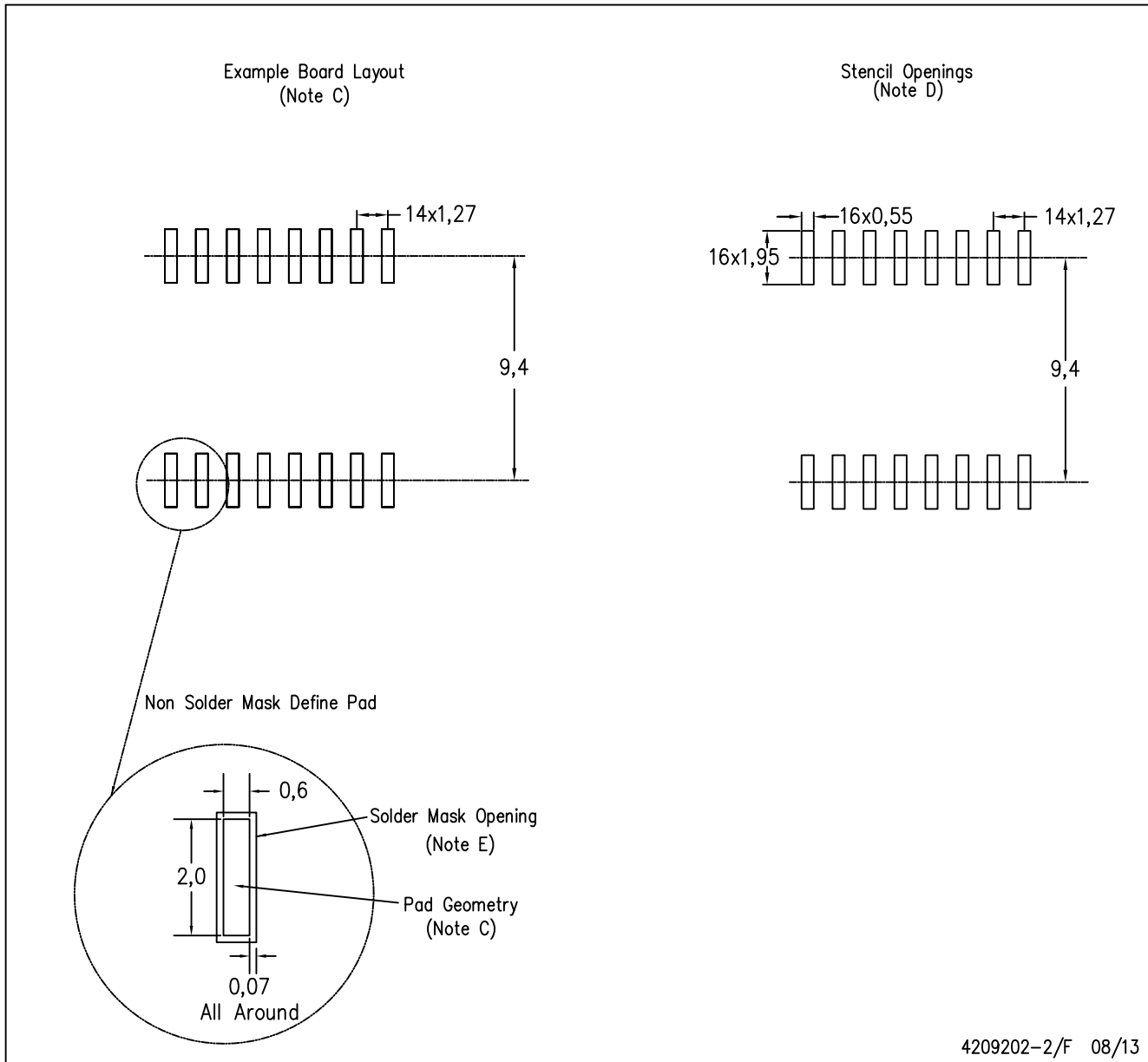
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AA.

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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